

40V N-Channel MOSFETs

General Description

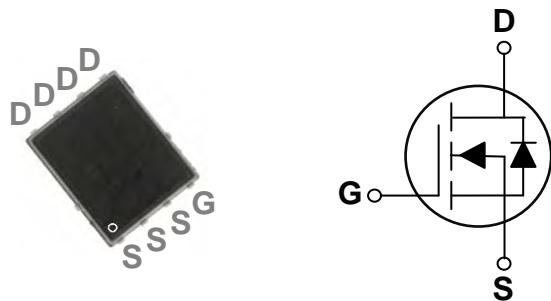
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDS(ON)	ID
40V	2.8mΩ	100A

Features

- 40V, 100A, RDS(ON) = 2.8mΩ @ VGS = 10V
- Improved dv/dt capability
- Fast switching
- Green Device Available

PPAK5x6 Pin Configuration



Applications

- MB / VGA / Vcore
- POL Applications
- SMPS 2nd SR

Absolute Maximum Ratings (T_c=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	40	V
V _{GS}	Gate-Source Voltage	± 20	V
I _D	Drain Current – Continuous (T _c =25 °C)	100	A
	Drain Current – Continuous (T _c =100 °C)	63	A
I _{DM}	Drain Current – Pulsed ¹	400	A
EAS	Single Pulse Avalanche Energy ²	312	mJ
IAS	Single Pulse Avalanche Current ²	79	A
P _D	Power Dissipation (T _c =25 °C)	135	W
	Power Dissipation – Derate above 25 °C	1.08	W/°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction to ambient	---	62	°C/W
R _{θJC}	Thermal Resistance Junction to Case	---	0.92	°C/W



FTK4960DFN56

40V N-Channel MOSFETs

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	40	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=1\text{mA}$	---	0.03	---	$\text{V}/^\circ\text{C}$
I_{DSs}	Drain-Source Leakage Current	$V_{\text{DS}}=40\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{\text{DS}}=32\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA

On Characteristics

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ³	$V_{\text{GS}}=10\text{V}$, $I_D=25\text{A}$	---	2.2	2.8	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_D=12\text{A}$	---	2.6	3.5	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D = 250\mu\text{A}$	1.2	1.6	2.5	V
			---	-5	---	$\text{mV}/^\circ\text{C}$
g_{fs}	Forward Transconductance	$V_{\text{DS}}=10\text{V}$, $I_D=2\text{A}$	---	16	---	S

Dynamic Characteristics

Q_g	Total Gate Charge ^{3,4}	$V_{\text{DS}}=20\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_D=10\text{A}$	---	44.4	80	nC
Q_{gs}	Gate-Source Charge ^{3,4}		---	9.6	18	
Q_{gd}	Gate-Drain Charge ^{3,4}		---	16	30	
$T_{\text{d(on)}}$	Turn-On Delay Time ^{3,4}	$V_{\text{DD}}=20\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=6\Omega$ $I_D=1\text{A}$	---	28	50	ns
T_r	Rise Time ^{3,4}		---	3.2	6.5	
$T_{\text{d(off)}}$	Turn-Off Delay Time ^{3,4}		---	89	160	
T_f	Fall Time ^{3,4}		---	14	28	
C_{iss}	Input Capacitance		---	4940	7800	pF
C_{oss}	Output Capacitance	$V_{\text{DS}}=25\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$	---	425	800	
C_{rss}	Reverse Transfer Capacitance		---	170	330	
R_g	Gate resistance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=0\text{V}$, $F=1\text{MHz}$	---	1.4	2.8	Ω

Drain-Source Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	100	A
			---	---	200	A
V_{SD}	Diode Forward Voltage ³	$V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=79\text{A}$., Starting $T_J=25^\circ\text{C}$
3. The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.

40V N-Channel MOSFETs

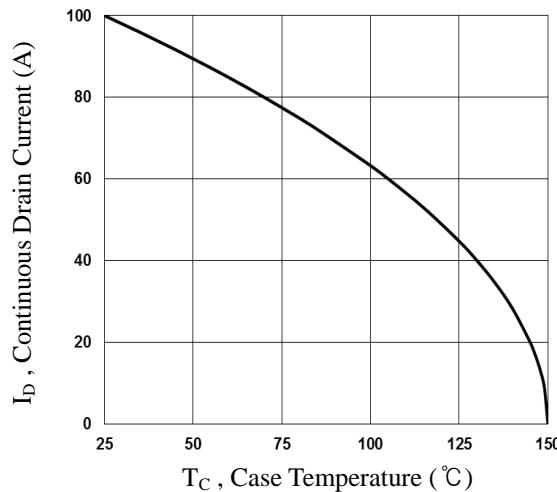


Fig.1 Continuous Drain Current vs. T_C

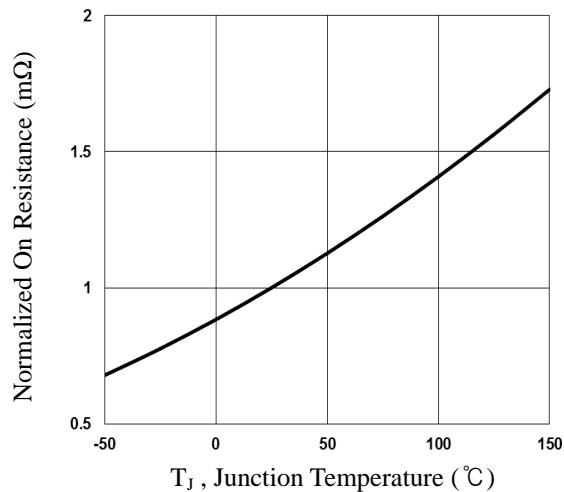


Fig.2 Normalized RDS(on) vs. T_J

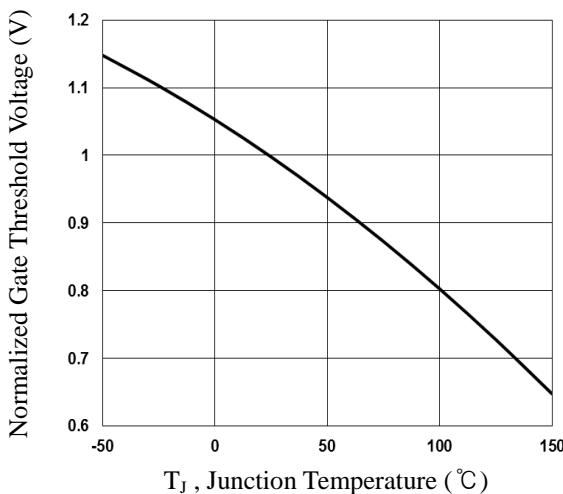


Fig.3 Normalized V_{th} vs. T_J

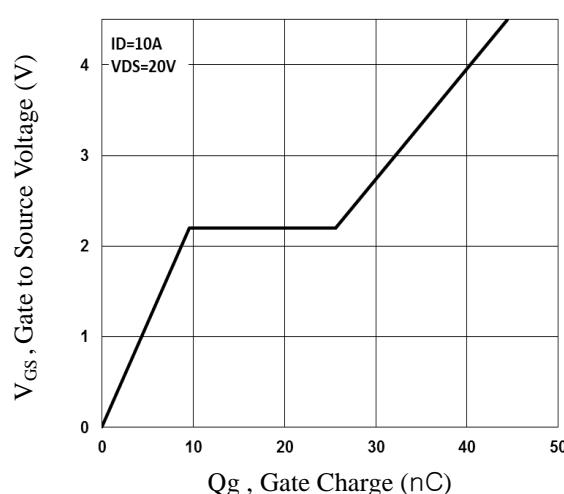


Fig.4 Gate Charge Waveform

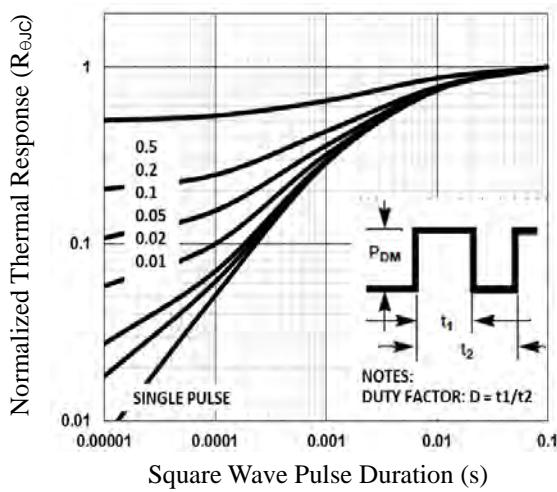


Fig.5 Normalized Transient Impedance

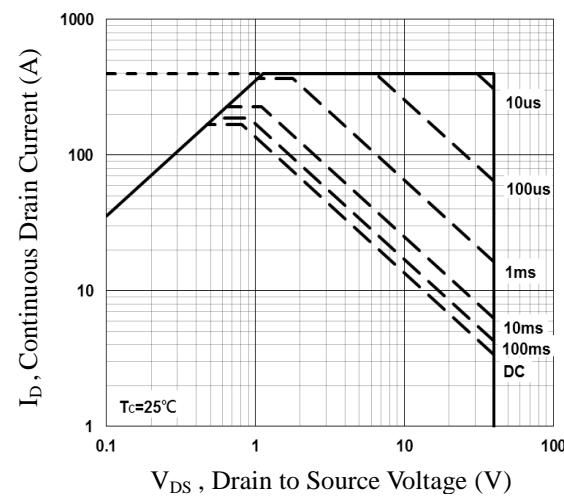


Fig.6 Maximum Safe Operation Area

40V N-Channel MOSFETs

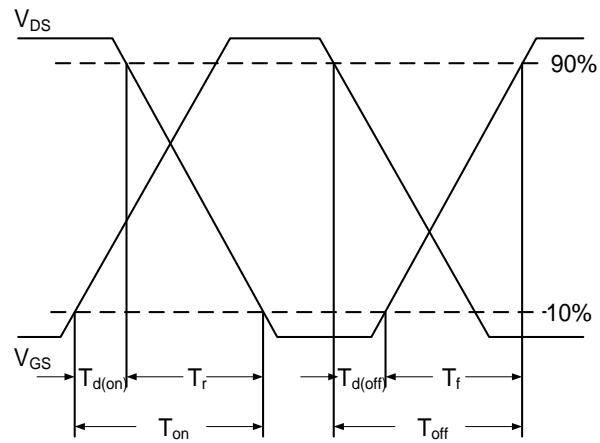


Fig.7 Switching Time Waveform

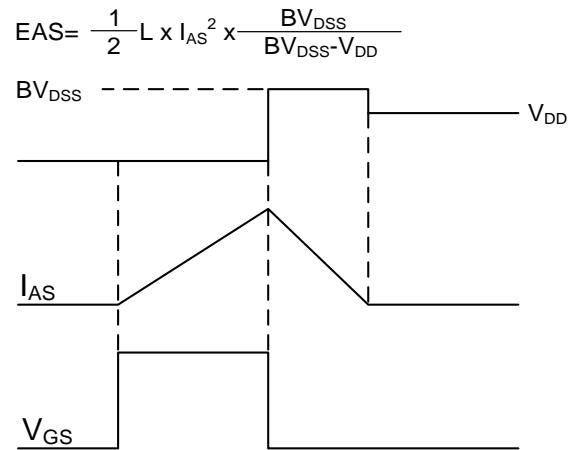
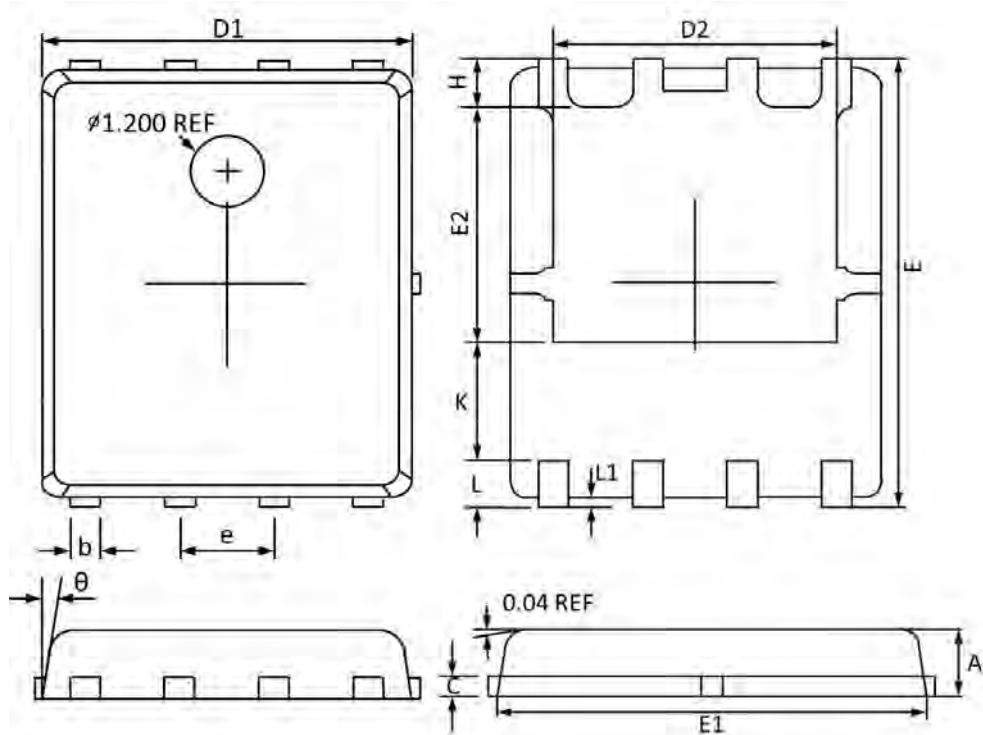


Fig.8 EAS Waveform

40V N-Channel MOSFETs

PPAK5x6 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.100	0.800	0.043	0.031
b	0.510	0.330	0.020	0.013
C	0.300	0.200	0.012	0.008
D1	5.100	4.800	0.201	0.189
D2	4.100	3.610	0.161	0.142
E	6.200	5.900	0.244	0.232
E1	5.900	5.700	0.232	0.224
E2	3.780	3.350	0.149	0.132
e	1.27BSC		0.05BSC	
H	0.700	0.410	0.028	0.016
K	1.500	1.100	0.059	0.043
L	0.710	0.510	0.028	0.020
L1	0.200	0.060	0.008	0.002